

Appendix A.9 5x6 B devices

Device outline

Figure A.9.1 shows the outline for these devices. The relative pad positions are controlled to an accuracy of $\pm 0.050\text{mm}$. For full dimensions and tolerances of each device, and to find out its size and outline, refer to the relevant product data sheet and package outline drawing.

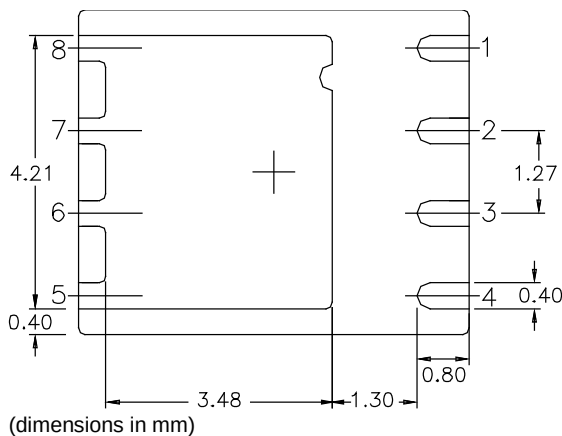


Figure A.9.1 5x6 B device outline

Substrate/PCB layout

Evaluations have shown that the best overall performance is achieved using the substrate/PCB layout shown in Figure A.9.2 (a and b).

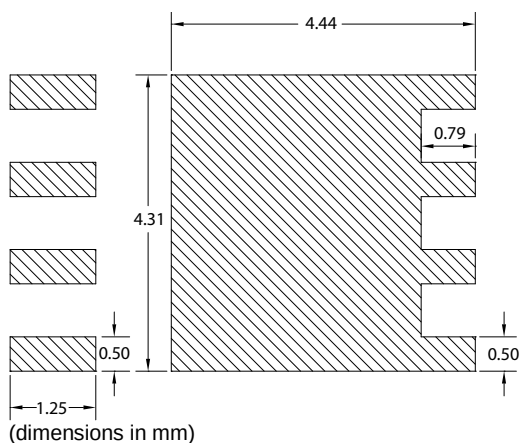


Figure A.9.2(a) 5x6 B substrate/PCB layout

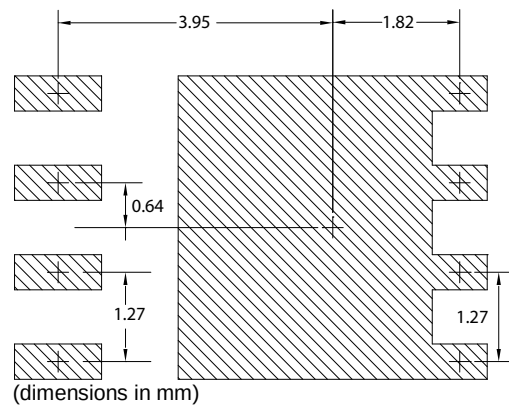


Figure A.9.2(b) 5x6 B substrate/PCB layout

Stencil design

Evaluations have shown that the best overall performance is achieved using the stencil design shown in Figure A.9.3 (a and b).

Note: This design is for a stencil thickness of 0.127mm (0.005"). The reduction should be adjusted for stencils of other thicknesses.

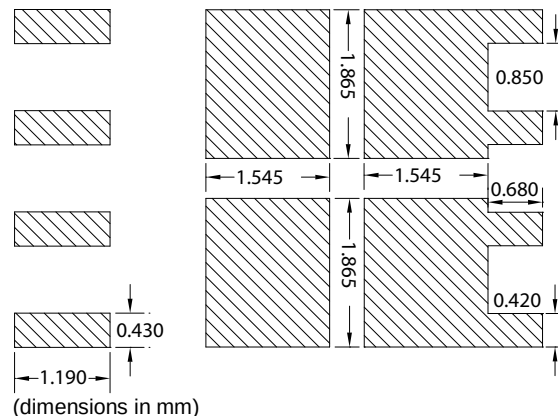


Figure A.9.3(a) 5x6 B stencil design

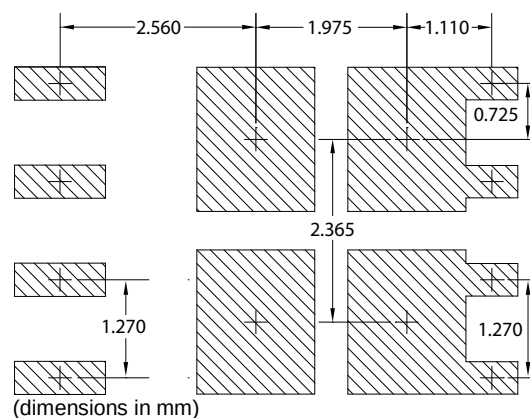


Figure A.9.3(b) 5x6 B stencil design